

Materials Declaration

Package	LFCSP
Body Size	3 X 3 X 0.85
LeadCount	8
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84	5.80 E-03	274132
Mutiaromatic Resin	16	1.11 E-03	52209
Subtotal		6.91 E-03	326341

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.17 E-02	553130
Fe	2.35	2.88 E-04	13607
Zn	0.12	1.40 E-05	661
P	0.03	4.00 E-06	189
Subtotal		1.20 E-02	567588

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	3.13 E-04	14789

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.61 E-04	17056

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.22 E-04	5764

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	1.05 E-03	49610

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70	2.79 E-04	13182
Resin	21	8.40 E-05	3969
Metal Oxide	3	1.20 E-05	567
Amine	3	1.20 E-05	567
Gamma Butyrolactone	3	1.20 E-05	567
Subtotal		3.99 E-04	18852

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S

Package Totals

Weight (g)	PPM
2.12 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.



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Materials Declaration

Package	LFCSP
Body Size	3 X 3 X 0.85
LeadCount	8
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84	5.80 E-03	273744
Mutiaromatic Resin	16	1.11 E-03	52135
Subtotal		6.91 E-03	325879

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.17 E-02	552347
Fe	2.35	2.88 E-04	13588
Zn	0.12	1.40 E-05	661
P	0.03	4.00 E-06	189
Subtotal		1.20 E-02	566785

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	3.13 E-04	14768

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.32 E-04	15664
Pb	15	5.90 E-05	2784
Subtotal		3.91 E-04	18448

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.22 E-04	5756

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	1.05 E-03	49540

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70	2.79 E-04	13163
Resin	21	8.40 E-05	3963
Metal Oxide	3	1.20 E-05	566
Amine	3	1.20 E-05	566
Gamma Butyrolactone	3	1.20 E-05	566
Subtotal		3.99 E-04	18825

Package Totals

Weight (g)	PPM
2.12 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S

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